

AEC/APC Symposium Asia 2019 SPONSORSHIP

November 13, 2019, Tokyo, Japan

Hidetaka Nishimura
Chairman, AEC/APC Symposium Asia 2019 Executive Committee
Renesas Electronics Corporation

Hidenori Kakinuma
Chairman, AEC/APC Symposium Asia 2019 Program Committee
Toshiba Memory Corporation

It is our great pleasure to announce that The 7th annual AEC/APC Symposium Asia 2019 will be held on November 13, 2019 at National Center of Sciences Building (Gakujutsu Sogo Center), Tokyo which is sponsored by ISSM (International Symposium on Semiconductor Manufacturing).

The program is consist of keynote speech, tutorial speeches, oral speeches, poster presentations and supplier exhibition. This year, the symposium puts the subtitle” Creating new value with digital twin based on data science”. AEC/APC Symposium Asia continues to contribute to the growth of the semiconductor industry through its infrastructure for networking, discussion, and information sharing among the world's professionals. We would like you to cooperate with us by supporting the AEC/APC Symposium Asia 2019. Please see the benefit of AEC/APC Symposium Asia 2019 sponsorship.

Conference Overview

Date: November 13, 2019

Location: National Center of Sciences Building (Gakujutsu Sogo Center)
2-1-2 Hitotsubashi Chiyoda-ku, Tokyo 101-0003, Japan
Tel: +81 3 4212-3900 Fax: +81 3 4212-3910

Sponsored by: International Symposium on Semiconductor Manufacturing (ISSM)

Supported by: Japan Electronics and Information Technology Industries Association
Semiconductor Equipment Association of Japan (SEAJ)
Semiconductor Equipment and Materials International (SEMI)

In conjunction with: Dry Process Symposium (DPS)

Area of Interest: Equipment and Process Control

- FDC (Fault detection and classification)
- SPC (Statistical process control)
- Run-to-run Control
- RMS (Recipe Management System)
- Model-based Process Control
 - Physical and chemical process models
 - Soft sensor
 - Virtual metrology
- Tool Data Acquisition and Analysis
 - Data collection
 - Sensor development
 - Failure and Yield Analysis
 - Statistical approaches
 - Bigdata Analysis
 - AI, Machine Learning
 - Enhanced equipment quality Assurance
- APC Strategy
 - Future Needs and opportunities
 - SDGs (Sustainable Development Goals)
 - Standard
- Region Expansion
 - Back-end process
 - MEMS (MEMS)
 - Display device
 - Solar panel
 - Battery

About AEC/APC Symposium

AEC/APC symposium calls its annual conference in North America, Europe, and Asia. The suppliers of the device, the equipment, the material, the software, the sensor, and the metrology shall meet, and discuss the more intelligent and the higher productive manufacturing system in the conferences. The conference is held in Taiwan and Japan every other year. AEC/APC is called the core of the scientific manufacturing technology. The technology has created the extensive progress of the productivity improvement and the yield improvement in the semiconductor manufacturing area. The technology discussed in the conferences has been applied and used in the process technology of LCD,PV and Battery.

In Japan, the 7th conference is called in this year. Since 2007, the conference has discussed the scientific manufacturing technology using the data which can monitor the manufacturing equipment and the process conditions.

The symposium is a very good chance among the technical authorities from Japan and from out of Japan to share their knowledge and technologies in AEC/APC area. The symposium can also be a very good chance for the professionals of the process control industry such as semiconductor to meet and discuss.

Today, this area already forms the core part of the manufacturing engineering technology.

The role of this symposium is very important, since people can share the information and the directions of the process control improvement, the equipment productivity improvement, and the material source reduction for the future.

*AEC: Advanced Equipment Control, APC: Advanced Process Control

Fact Sheet

Event	1	2	3	4	5	6
Year	2007*	2009	2011	2013	2015	2017
Attendees	435	233	173	167	195	243
Countries	8	6	7	4	6	4
Sponsors	14	9	7	16	11	11
Exhibitors	17	7	3	6	5	6

*2days

Organization

-Executive Committee-

Chair

Hidetaka Nishimura

Renesas Electronics Corporation

Member

Toshiyuki Uchino

Kokusai Electric Corporation

-Japan Program Committee-

Chair

Hidenori Kakinuma

Toshiba Memory Corporation

Vice-Chair

Sumika Arima

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Members

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Tokyo Electron Ltd.

Kazutaka Nagashima

Toshiba Electronic Devices & Storage Corporation

Tomoya Tanaka

TowerJazz Panasonic Semiconductor

-Advisor-

Koji Maekawa

Former PDF Solutions, Inc.

AEC/APC Symposium Asia 2019 Sponsorship

	Platinum	Gold	Silver	Bronze
Sponsorship Fee	¥800,000	¥500,000	¥300,000	¥80,000
AEC/APC Symposium Asia 2019 Invitation (Free)				
Free ticket(s) for AEC/APC Symposium Asia 2019(Tutorial session excluded)	12	7	4	1
AEC/APC Symposium Asia 2019 Website				
Company logo placed on homepage	Yes	Yes	Yes	Yes
Company logo placed on right-hand side of website	Upper	Middle	Lower	Lower
Link to company homepage	Yes	Yes	Yes	Yes
AEC/APC Symposium Asia 2019 Proceedings (Download) & Brochure				
Recognition of sponsorship in meeting materials along with company logo and link to corporate website (User would need to have Internet access when viewing the proceedings)	Upper	Middle	Lower	Lower
Company logo printed in color on the brochure on site	Upper	Middle	Lower	Lower
AEC/APC Symposium Asia 2019 Screen at site				
Company logo on the screen of interval	Upper	Middle	Lower	Lower
Company logo poster at the Symposium Room	Upper	Middle	Lower	Lower

Exhibition (with Sponsorship)	¥100,000
Exhibition Only	¥120,000

AEC/APC Symposium Asia 2019 Exhibition

Contact:

AEC/APC Symposium Asia 2019 Office
 C/O Semiconductor Portal, Inc.
 4F, Masonic 39MT Bldg., 2-4-5 Azabudai, Minato-ku, Tokyo 106-0041 Japan
 TEL: +81-3-5733-4971
 E-mail: aecapc_2019@semiconportal.com